

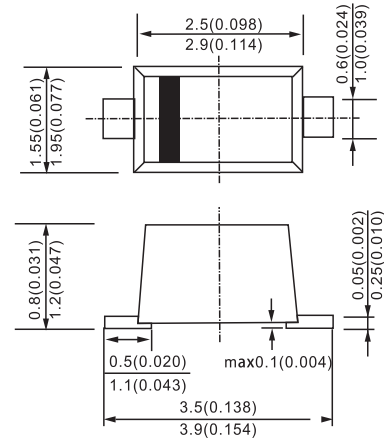
FEATURES

- Glass passivated device
- Ideal for surface mouted applications
- Low leakage current
- Metallurgically bonded construction
- High temperature soldering:
250 /10 seconds at terminals

MECHANICAL DATA

- Case: JEDEC SOD-123FL, molded plastic over passivated chip
- Terminals: Solder Plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Weight: 0.006 ounces, 0.02 gram
- Mounting position: Any

SOD-123FL



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

		S07B	S07D	S07G	S07J	S07M	UNITS
Device marking code		B0	D0	G0	J0	M0	
Maximum recurrent peak reverse voltage	V_{RRM}	100	200	400	600	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	700	V
Maximum DC blocking voltage	V_{DC}	100	200	400	600	1000	V
Maximum average forward rectified current $T_A=65$ (NOTE 1)	$I_{(AV)}$	0.7					A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load $T_L=25$	I_{FSM}	25					A
Typical thermal resistance (NOTE 2)	$R_{j\theta A}$	180					K/W
Operating temperature range	T_j	- 55 --- + 150					
Storage temperature range	T_{STG}	- 55 --- + 150					

NOTES:1.Averaged over any 20 ms period.

2. Thermal resistance junction to ambient, 6.0 mm² copper pads to each terminal.

RATINGS AND CHARACTERISTIC CURVES S07B THRU S07M

FIG.1 – TYPICAL FORWARD CHARACTERISTIC

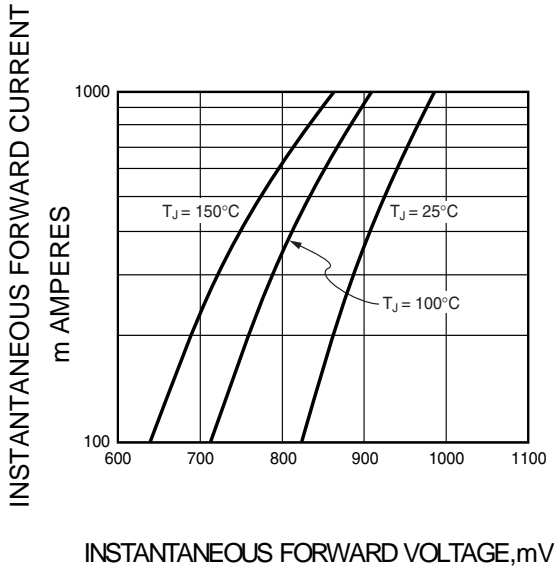


FIG.2 – TYPICAL JUNCTION CAPACITANCE

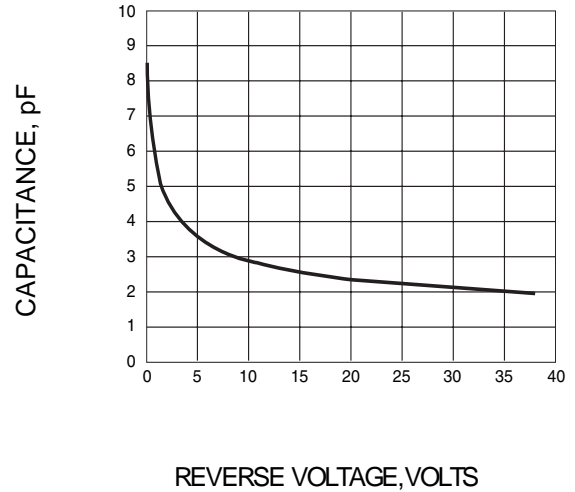


FIG.3 – TYPICAL INSTANTANEOUS REVERSE CHARACTERISTICS

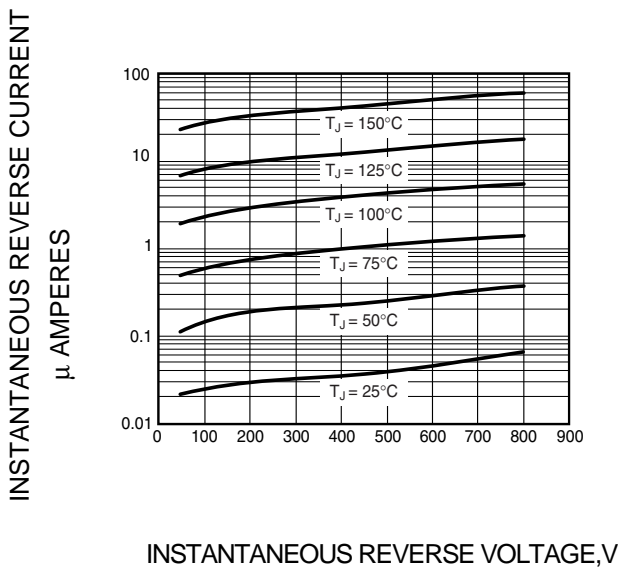


FIG.4 – FORWARD DERATING CURVE

